

## AMENDMENT TO CLAIMS

### *In the Claims*

Please **AMEND** claims 1, 3-5, 7, and 8

Please **ADD** new claims 11-14 as follows.

A copy of all pending claims and a status of the claims is provided below.

1. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:

preparing an etchable upper substrate and an etchable lower substrate;

forming image display devices means on an inner surface of the lower substrate in such a way that the at least two image display devices means are isolated from each other;

combining the upper substrate and the lower substrate together so that the image display devices means are individually sealed up;

etching outer surfaces of the upper substrate and the lower substrate; and

cutting the combined upper and lower substrates in units of an image display device means such that each image display device means is separate,

wherein each of the image display devices are surrounded by an inner sealant and all of the image display devices and the inner sealant are surrounded by an outer sealant.

2. (Original) The method of claim 1, wherein the upper and lower substrates are formed of a glass-based material.

3. (Currently Amended) The method of claim 1, wherein the combining ~~step~~ comprises attaching an unetchable protection film to all of each lateral side of the combined upper and lower substrates.
4. (Currently Amended) The method of claim 1, wherein during the etching ~~step~~, the outer surfaces of the upper and lower substrates are etched so that the upper substrate and the lower substrate each have a total thickness of at most 0.5mm.
5. (Currently Amended) A method for manufacturing a thin flat panel display, the method comprising:
- preparing ~~for~~ an etchable upper substrate and an etchable lower substrate;
  - forming an image display device means on an inner surface of the lower substrate;
  - combining the upper substrate and the lower substrate together so that the image display device means is sealed up; and
  - etching ~~the~~ outer surfaces of the upper substrate and the lower substrate,
- wherein each of the image display devices are surrounded by an inner sealant and all of the image display devices and the inner sealant are surrounded by an outer sealant.
6. (Original) The method of claim 5, wherein the upper substrate and the lower substrate are formed of a glass-based material.

7. (Currently Amended) The method of claim 5, wherein the combining ~~step~~ comprises attaching an unetchable protection film to all of each lateral side of the combined upper and lower substrates.
8. (Currently Amended) The method of claim 5, wherein during the etching step, the outer surfaces of the upper substrate and the lower substrate are etched so that the upper and lower substrates each have a total thickness of at most 0.5mm.
9. (Withdrawn) A thin flat panel display comprising:  
an upper substrate and a lower substrate which are etched to have a thickness of 0.5mm or smaller and combined together;  
an image display means formed on an inner surface of the lower substrate; and  
a protection film attached to the lateral sides of the combined upper and lower substrates.
10. (Withdrawn) The thin flat panel display of claim 9, wherein the image display means comprises:  
a first electrode layer;  
a luminescent layer formed on the first electrode layer; and  
a second electrode layer formed on the luminescent layer.
11. (New) The method according to claim 1, wherein the inner sealant completely surrounds each of the imaged display devices.

12. (New) The method according to claim 1, wherein the image display devices are organic EL display devices.

13. (New) The method according to claim 5, wherein the inner sealant completely surrounds each of the imaged display devices.

14. (New) The method according to claim 5, wherein the image display devices are organic EL display devices.